IN THE SPECIFICATION:

Please amend the paragraph beginning at page 13, line 13, and ending at page 13, line 18, as follows:

--Whether one side of each of the coil pattern section 1a, IC chip supporting section 1b, and connecting terminals 1c is exposed or whole surfaces thereof ~~is~~ are encapsulated can be just selected optionally according to a purpose of use, an operating environment, etc.–

Please amend the paragraph beginning at page 15, line 13, and ending at page 15, line 25, as follows:

--FIG. 6A shows an iron-nickel plate 20 patterned according to FIGS. 5A to 5D. The patterned iron-nickel plate 20 shown in FIG. 6A connects respective portions of the coil pattern section 1a with ~~a tying~~ tying sections 1e shown in FIG. 6E so that the coil pattern section 1a should be deformed in the shape of a spring in the direction perpendicular to the patterned iron-nickel plate 20. In addition, the tying sections partially connect the outermost periphery of the coil pattern section 1a to the outer frame section 1d. In addition, the tying sections 1e also ~~connects~~ connect to the IC chip supporting section 1b to prevent its deformation.--

Please amend the paragraph beginning at page 18, line 9, and ending at page 18, line 27, as follows:

--Next, at STEP 5, a method of encapsulating the IC chip 2 and the frame 25 for an IC tag by the encapsulating resin material 3 will be described with reference to FIG. 8. In FIG. 8, reference numeral 30 denotes a fixed die and reference numeral 31 denotes a movable

die. First, the frame 25 for an IC tag is held on the fixed die 30. At this time, the outer frame section 1d of the frame 25 for an IC tag is arranged so that the outer frame section 1d may be located in the outside of a mold cavity 32, into which the encapsulating resin material 3 is injected, and ~~that~~ the outer frame section 1d is not encapsulated with the encapsulating resin material 3. Next, the fixed die 30 and movable die 31 are opened after injecting the encapsulating resin material 3 into the mold cavity 32 and curing the encapsulating resin material 3, and the frame 25 for an IC tag covered with the encapsulating resin material 3 is taken out.--

Please amend the paragraph beginning at page 22, line 24, and ending at page 23, line 5, as follows:

--In the embodiments described above, although the IC tag with rectangular geometry is used and described as the examples as shown in FIGS. 1 and 11, geometry is not especially limited, and hence, for example, as shown in FIG. 14, round geometry can be used. In addition, as shown in FIG. 15, a coil pattern section may be divided into two portions and ~~arrange them~~ arranged, ~~and to arrange~~ with an IC chip arranged in a center section.--

Please amend the paragraph beginning at page 23, line 6, and ending at page 23, line 13, as follows:

--A semiconductor device according to the present invention can ~~use~~ be used as a non-contacting type IC card, an IC tag, or the like where an IC chip including a microprocessor and semiconductor memory such as RAM and ROM, and a coil for functioning as an electric

power supply and a communication antenna are mounted. Also, a battery for applying a voltage to the IC chip may be provided, if necessary.--